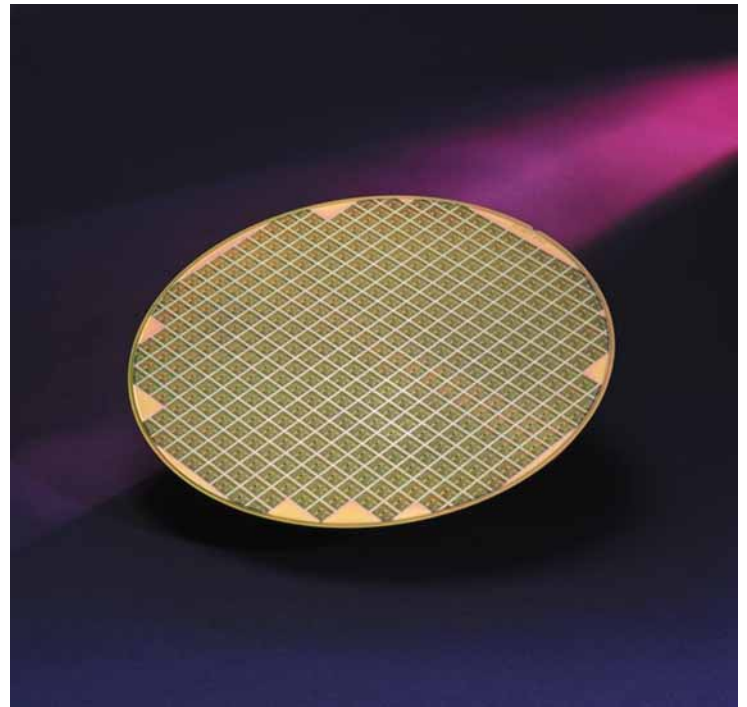
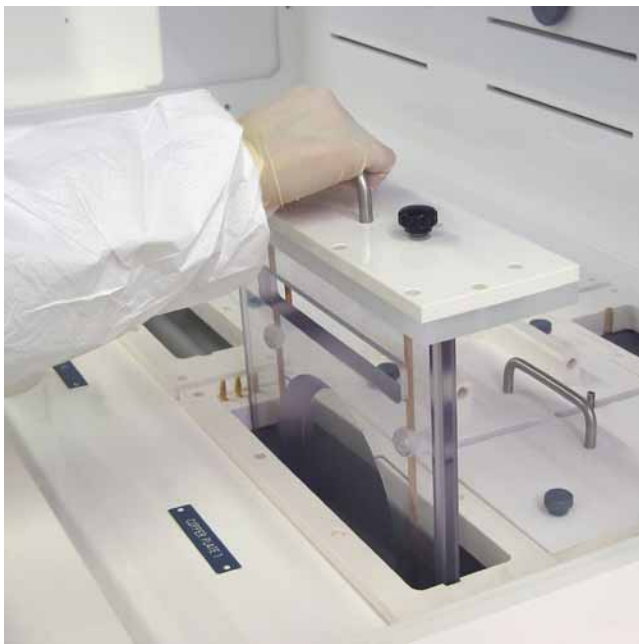


AuroStan H

Gold -Tin Alloy Plating Process

AuroStan H is a plating solution formulated to deposit semi-bright to bright eutectic Gold Tin alloy. The alloy ranges from 75 to 82-wt% Au content, with corresponding melting temperature between 280°C to 320°C. The alloy is useful in opto-electronic, semiconductor applications, for plating of larger area and as a low melting solder. The electrolyte is compatible with most photo resist systems.



Features and Benefits

1. AuroStan H deposits eutectic or near eutectic alloy from 5 to 7.5 ASF.
2. Excellent electrolyte stability
3. Excellent solderability characteristics
4. Compatible with most photoresist systems



Prototype plating is done on Technic's SEMCON 2000 which performs critical plating requirements with a high degree of uniformity and repeatability on wafers and other substrates from 50mm to 200 mm.



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